FORM PTO-1449 (Equivalent) U.S. Department of Commerce Patent and Trademark Office

U.S. Application Serial No. 08/995,108

Atty. Docket No. AM 1776

INFORMATION DISCLOSURE STATEMENT BY APPLICANT

(Use several sheets if necessary)

Peijun Ding et al.
Applicants

December 19, 1997
Filing Date

Unknown
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| FORM PTO-1449 (Equivalent) | U.S. Department of Commerce Patent and Trademark Office | U.S. Application Serial No. 08/995,108 | Atty. Docket No. AM-1776 |
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